

SEVENTEENTH ANNUAL

BiTS

Burn-in & Test Strategies Workshop

TM

March 6 - 9, 2016

**Hilton Phoenix / Mesa Hotel
Mesa, Arizona**

Archive- Session 3

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Session 3

Morten Jensen
Session Chair

BiTS Workshop 2016 Schedule

Frontiers Day

Monday March 7 - 4:30 pm

Stimulating Simulating

"Optimizing the PCB-to-socket-to-DUT interface"

Gert Hohenwarter - GateWave Northern, Inc.

"Characterize Only the High Speed Interconnect Performance"

Carol McCuen - R&D Altanova

"Modelling, Materials, and Madness"

Mike Gedeon - Materion

Modeling, Materials, and Madness

Mike Gedeon
Materion



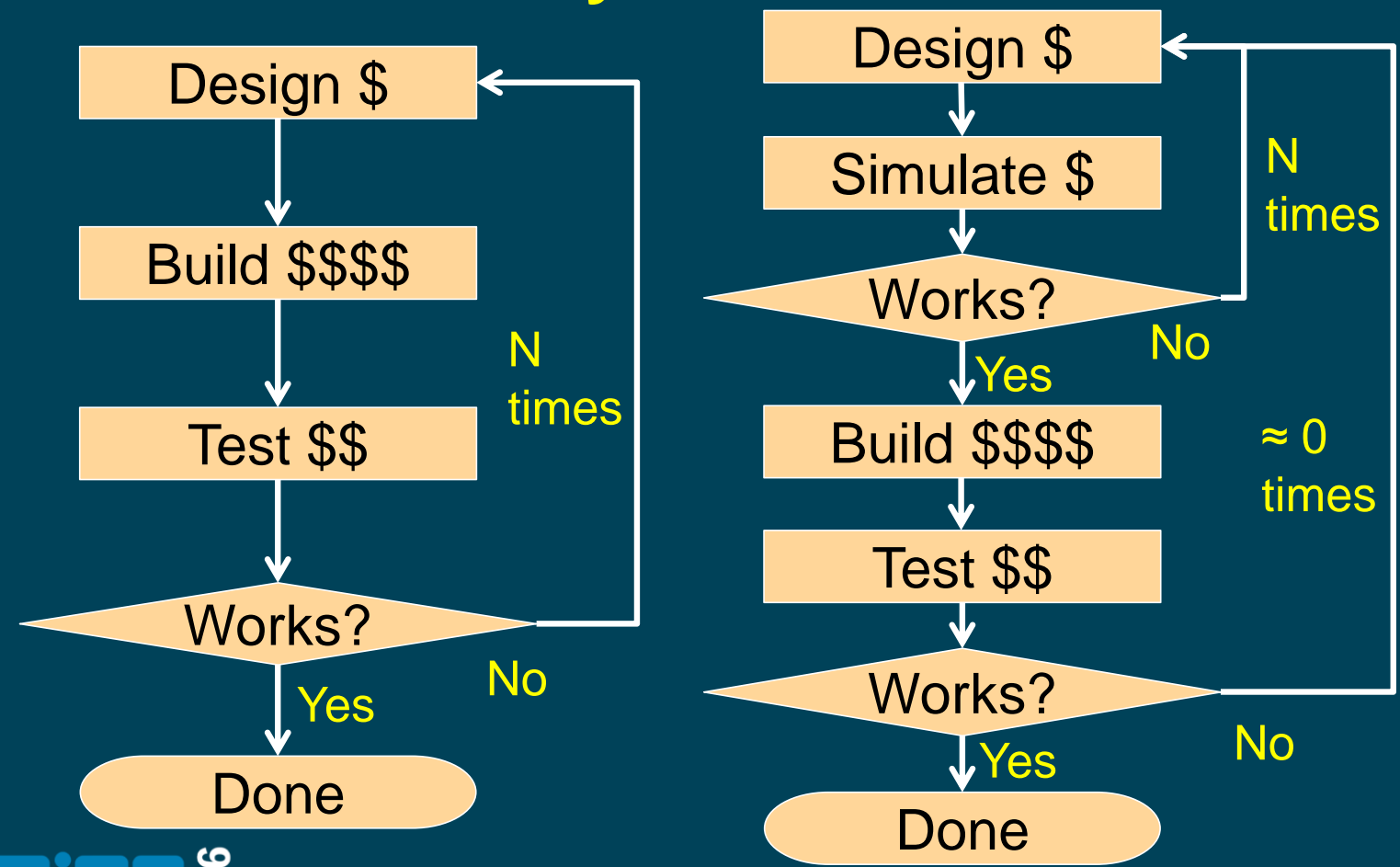
2016 BiTS Workshop
March 6 - 9, 2016



Computer Simulation

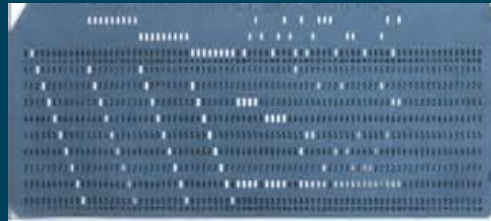
- FEA (Finite Element Analysis)
- CFD (Computational Fluid Dynamics)
- BEM (Boundary Element Method)
- SPICE (Simulation Program with Integrated Circuit Emphasis)
- And many, many more...

Why Simulate



Simulation – The Early Days

Input / Output Device



Typical User Interface



Typical Users



Typical System



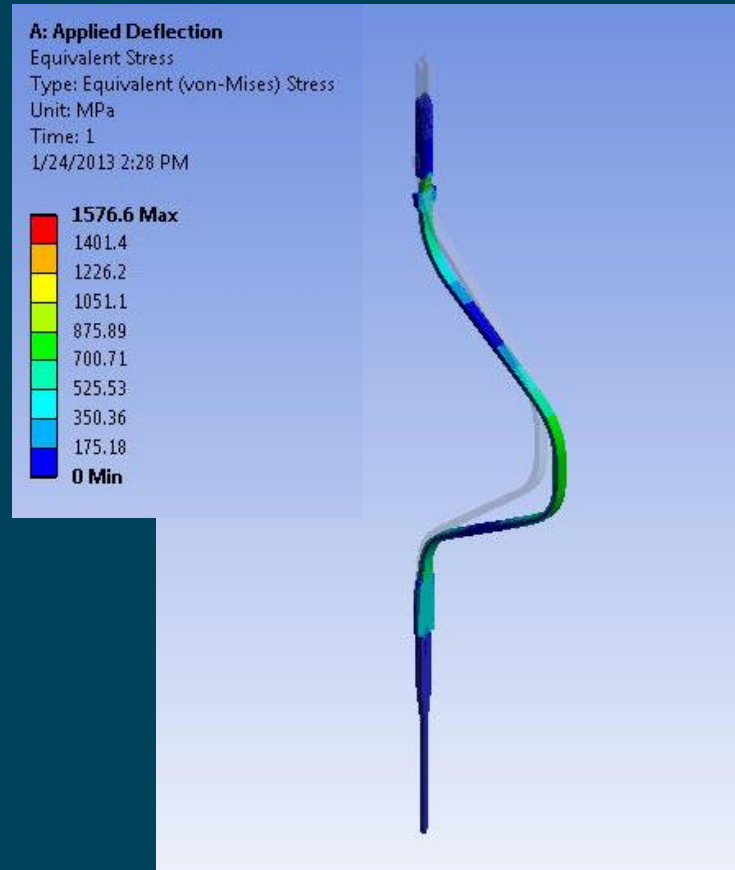
Simulation – Today



Simulation

Benefits

- Almost anyone can do it
- Produces convincing graphics
- Can increase your confidence of reliability



Simulation

Benefits

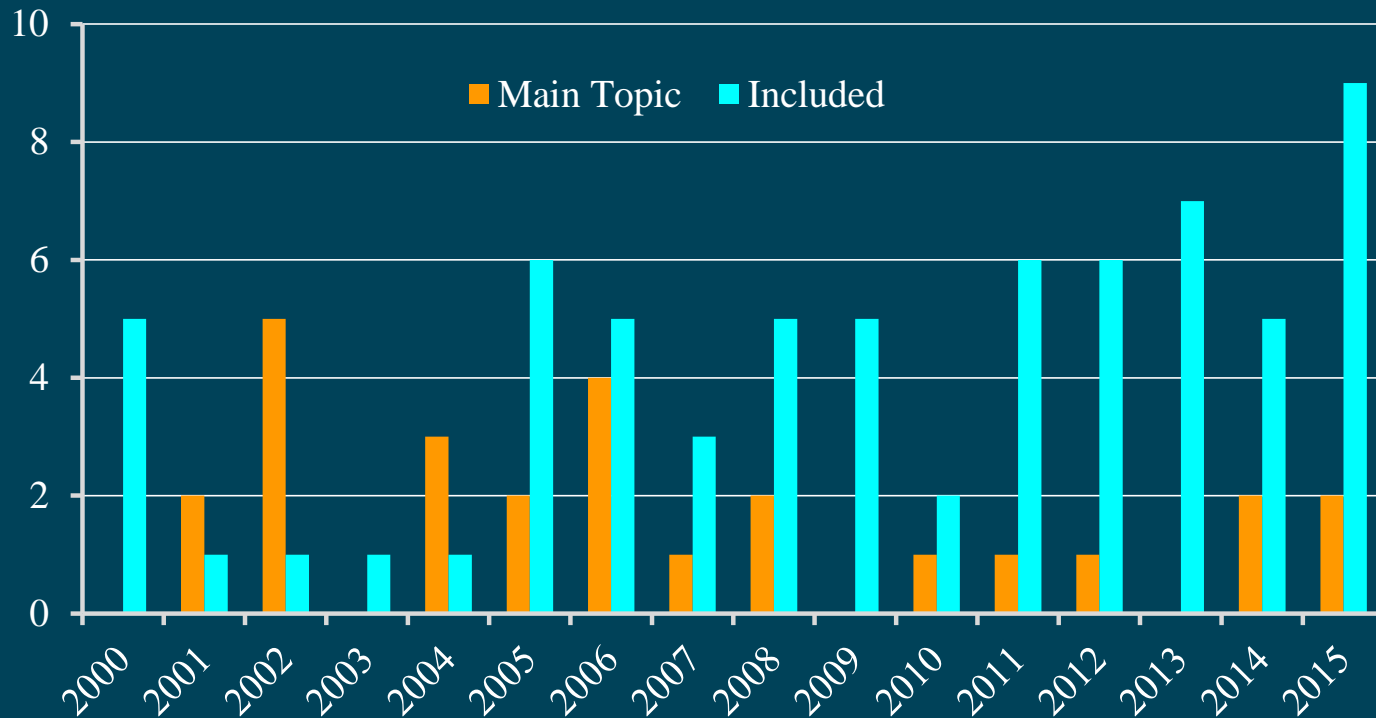
- Almost anyone can do it
- Produces convincing graphics
- Can increase your confidence of reliability

Disadvantages

- Almost anyone can do it
- Produces convincing graphics
- Can increase your confidence of reliability

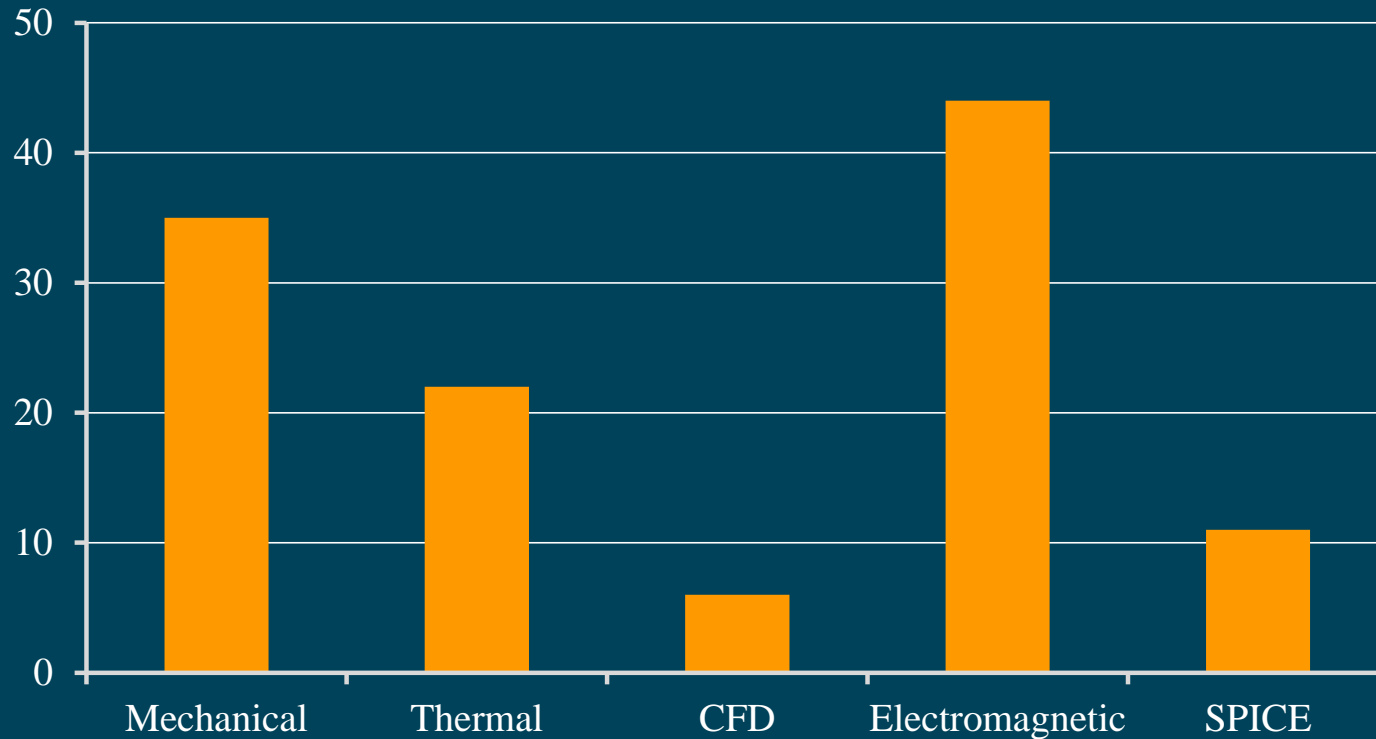
A History of Simulation at BiTS

Presentations on Simulation



A History of Simulation at BiTS

Presentations on Simulation



Simulation has Appeared in

- 78 Papers
- 4 Hot Topics Papers
- 2 Supplemental Papers
- 2 Tutorials
- 3 Posters
- 1 Panel Discussion
- 1 Invited Speaker Presentation
- 1 Tech Talk
- 1 Marketplace Report
- 1 Keynote Address

BiTS 2004

FEA Analysis of a Burn-in Socket Contact - Beware the use of Simple Models.

**Prasanth Ambady, Ray Mandeville and
James Forster**

**Texas Instruments,
Sensors & Controls, Attleboro, MA**

**2004 Burn-in Test Socket Workshop - March 7-10, 2004
Hilton Phoenix East/Mesa Hotel
Mesa, Arizona**



Beware the Use of Simple Models – BiTS 2004

- FEA is a tool which has revolutionized the world of design
- Care must be exercised to ensure that the results are meaningful
- Garbage in – Garbage out.
- Our understanding is imperfect - mistakes will still happen.
- Attempt to verify predications whenever possible.
- “It is difficult for outsiders to assess whether FEA work is being done effectively”.
- Peter Budgell (FEA Consultant)

BiTS 2006

Sources of Variation and Error in Finite Element Analysis

2006 Burn-in and Test Socket Workshop
March 12 - 15, 2006



Mike Gedeon
Brush Wellman Inc.

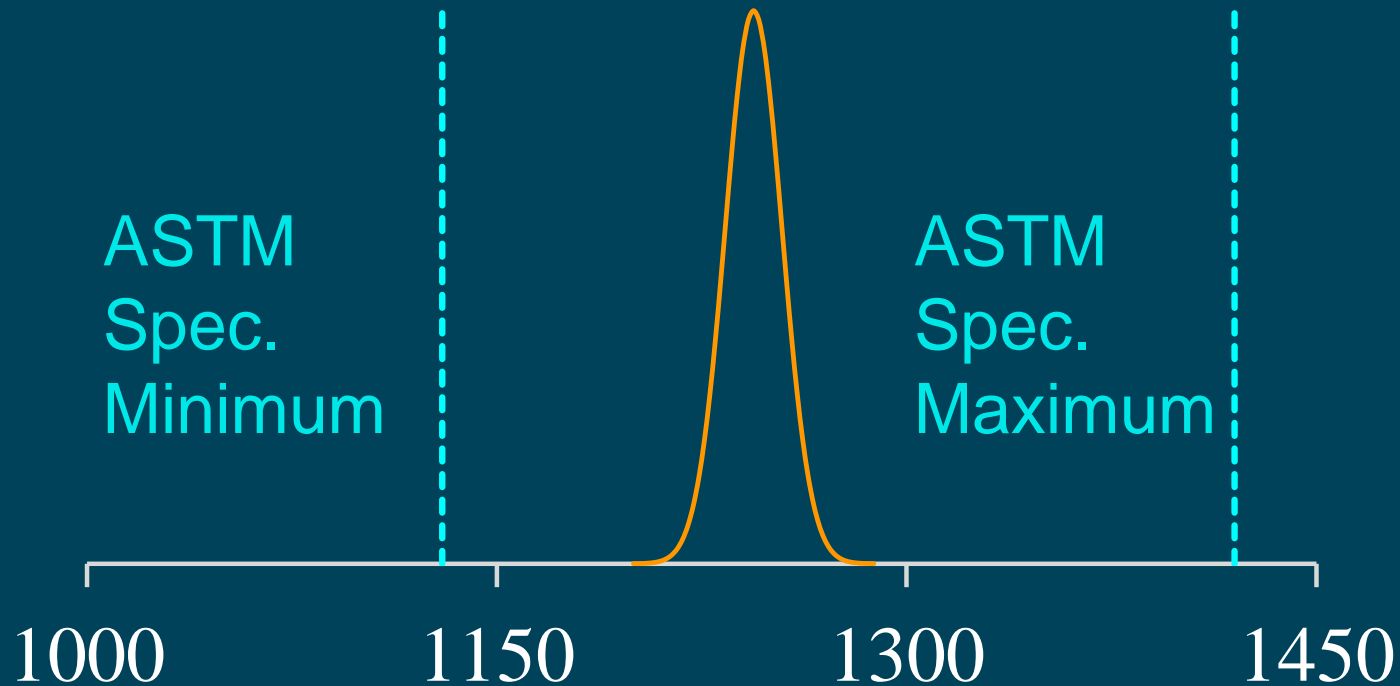


Sources of Variation and Error in FEA - BiTS 2006

- Oversimplification of model
- Element type/size
- Nonlinearities
- Definition of boundary/initial conditions
- Frictional effects
- Stiffness singularities
- Dimensional tolerances
- Property variation
- Residual stresses
- Edge condition/cross-section uniformity

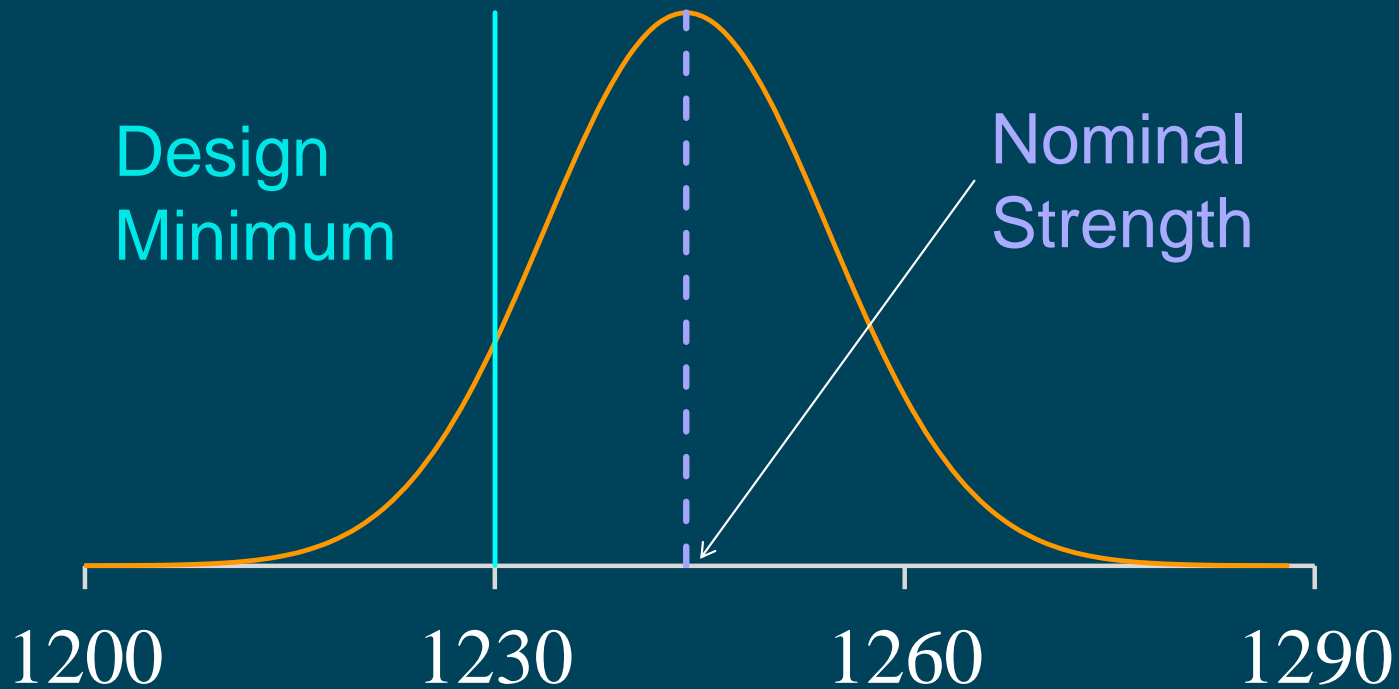
Know Your Spec's and Stats

Yield Strength Distribution



Problem!

Yield Strength Distribution



Remember

Price

(not necessarily cost)



Performance

Using Handbook/Library Data

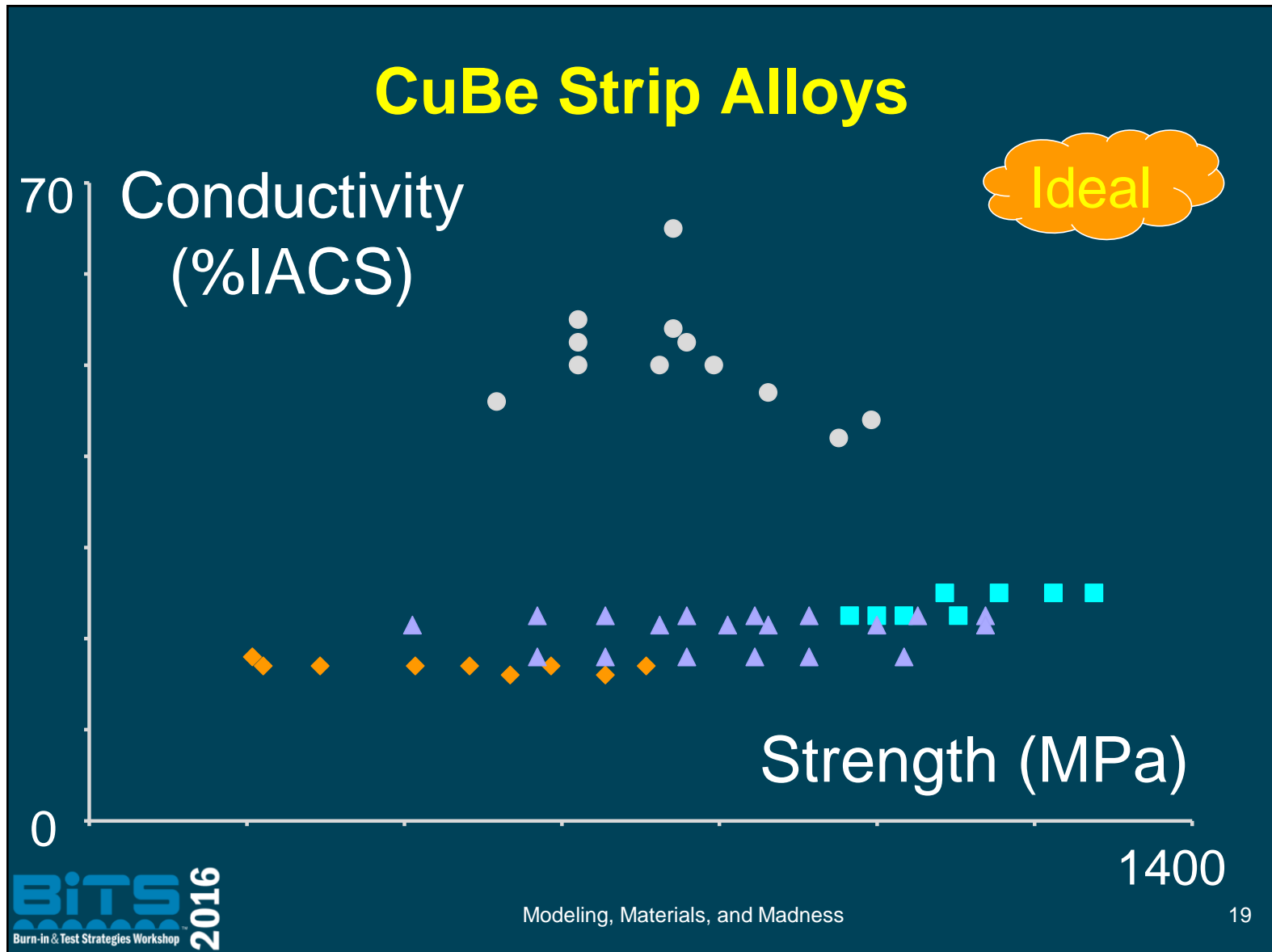
The screenshot shows a software window titled "Material" with a tree view on the left and a properties panel on the right. The tree view is expanded to "Copper Alloys" and "Beryllium Copper, UNS C17200" is selected. The properties panel shows the following settings:

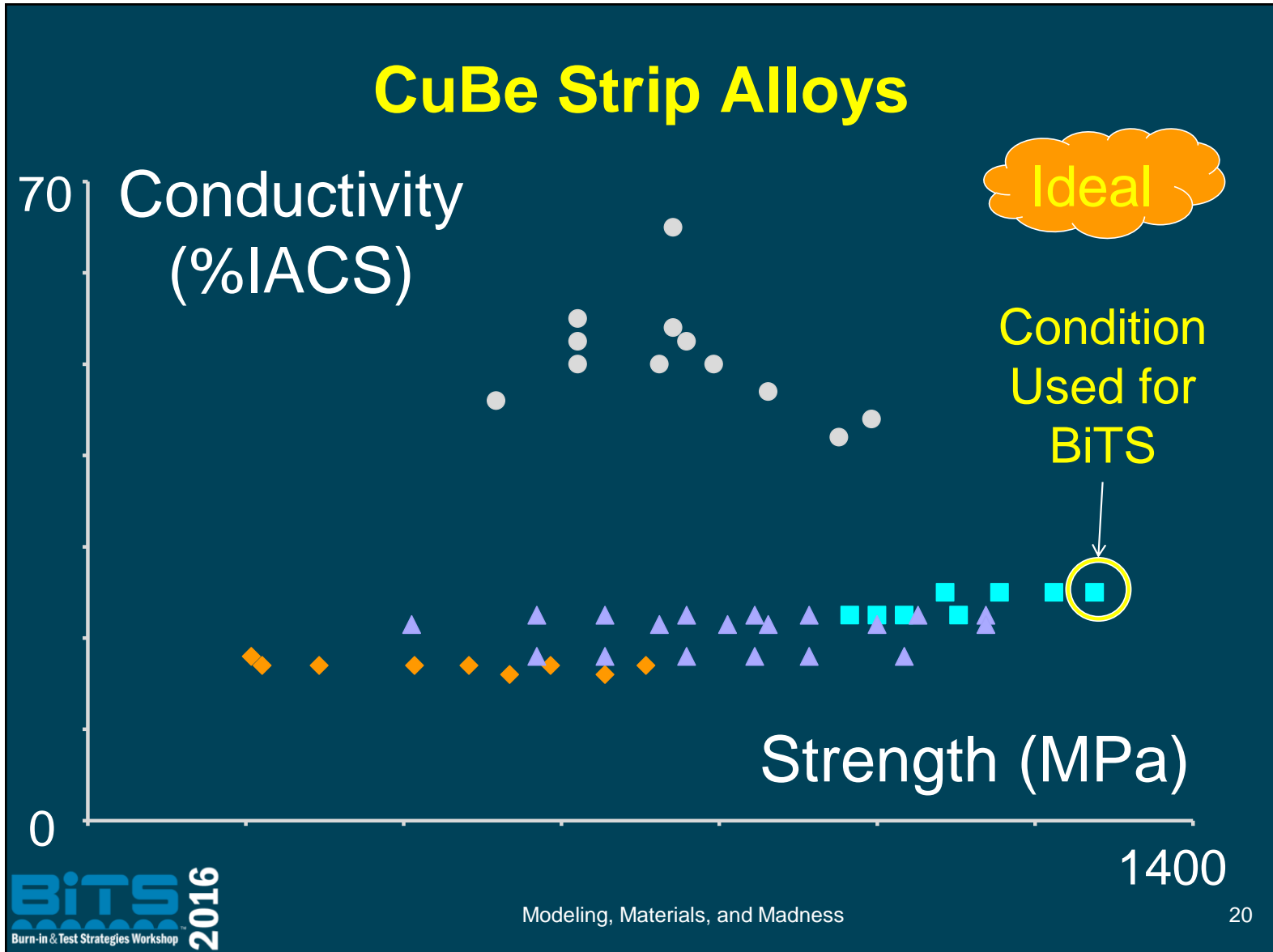
- Model Type: Linear Elastic Isotropic
- Units: SI - N/mm² (MPa)
- Category: Copper Alloys
- Name: Beryllium Copper, UNS C17200
- Description: (empty)
- Source: (empty)
- Sustainability: Defined

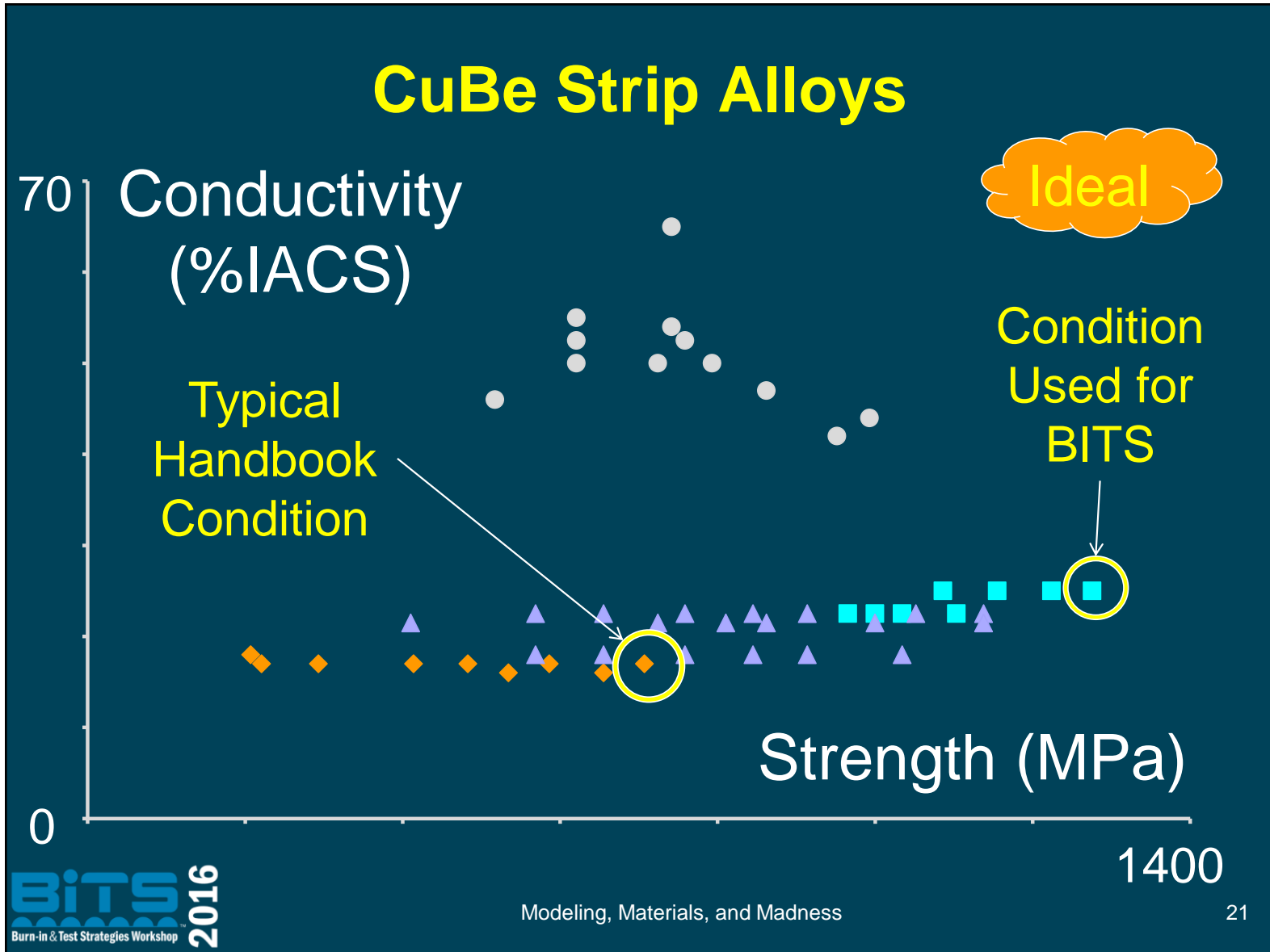
Below the properties panel is a table of material properties:

Property	Value	Units
Elastic Modulus in X	125000	N/mm ²
Poisson's Ratio in XY	0.3	N/A
Shear Modulus in XY	50000	N/mm ²
Mass Density	8250	kg/m ³
Tensile Strength in X	469	N/mm ²
Compressive Strength in X		N/mm ²
Yield Strength	172	N/mm ²
Thermal Expansion Coefficient in X	1.67e-005	/K
Thermal Conductivity in X	105	W/(m·K)
Specific Heat		J/(kg·K)
Material Damping Ratio		N/A

Buttons at the bottom of the window include Apply, Close, Save, Config..., and Help.







Using Handbook/Library Data

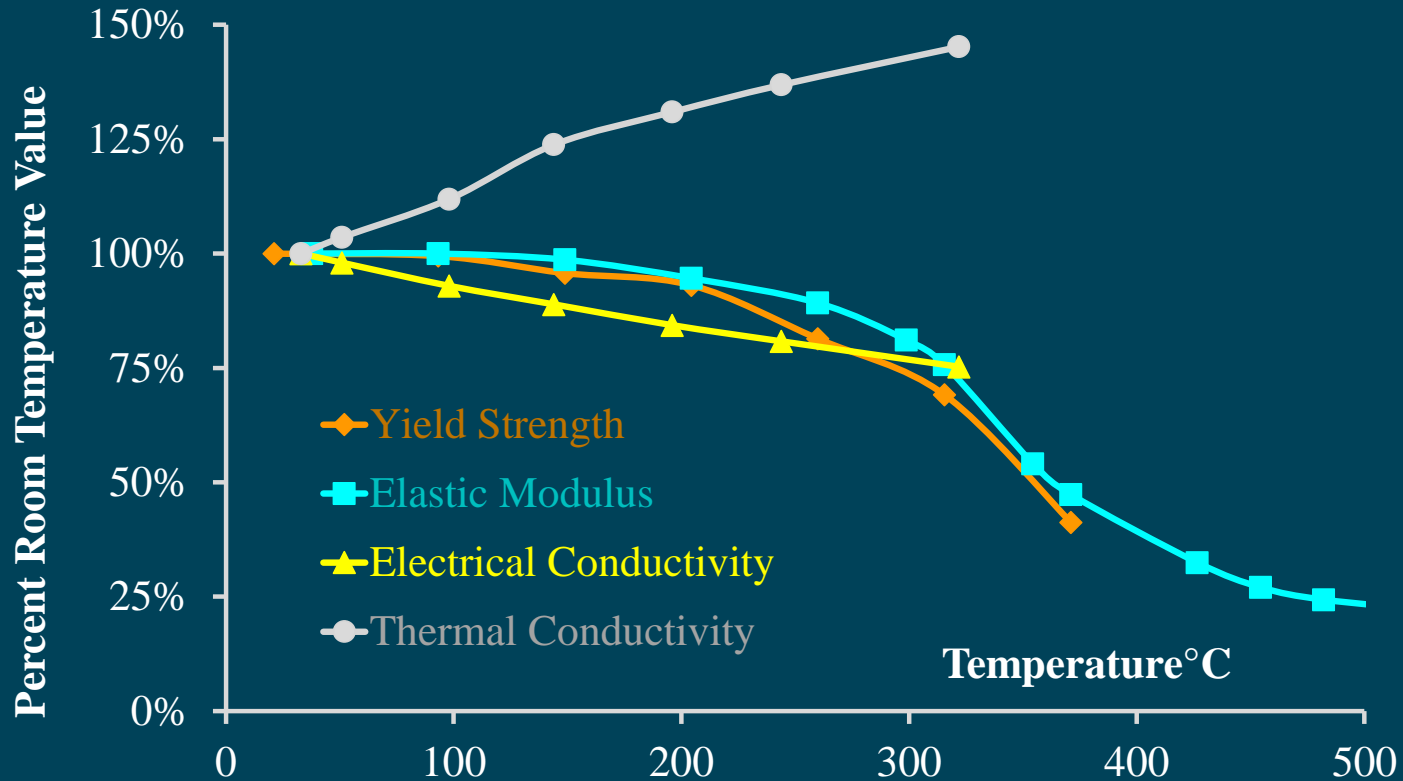
You're expecting this:



You may only have this:



Material Variation with Temperature



Types of Properties

Material Properties

- Known/measurable for each material
- Physical, mechanical, electrical, thermal, etc.

System Properties

- Combination of properties, loading & environmental conditions
- Coefficient of friction, contact resistance, etc.

Variation of Material Properties

- Material properties may be functions of
 - Temperature (Strength, Conductivity, Specific Heat, Toughness)
 - Strain Rate (Strength, Toughness)
 - Electric Field Strength (Permittivity)
 - Magnetic Field Strength (Permeability)
 - Pressure (Melting/Freezing Temperature)
 - Frequency (Dielectric Constant)
 - Time (Stress Relaxation)

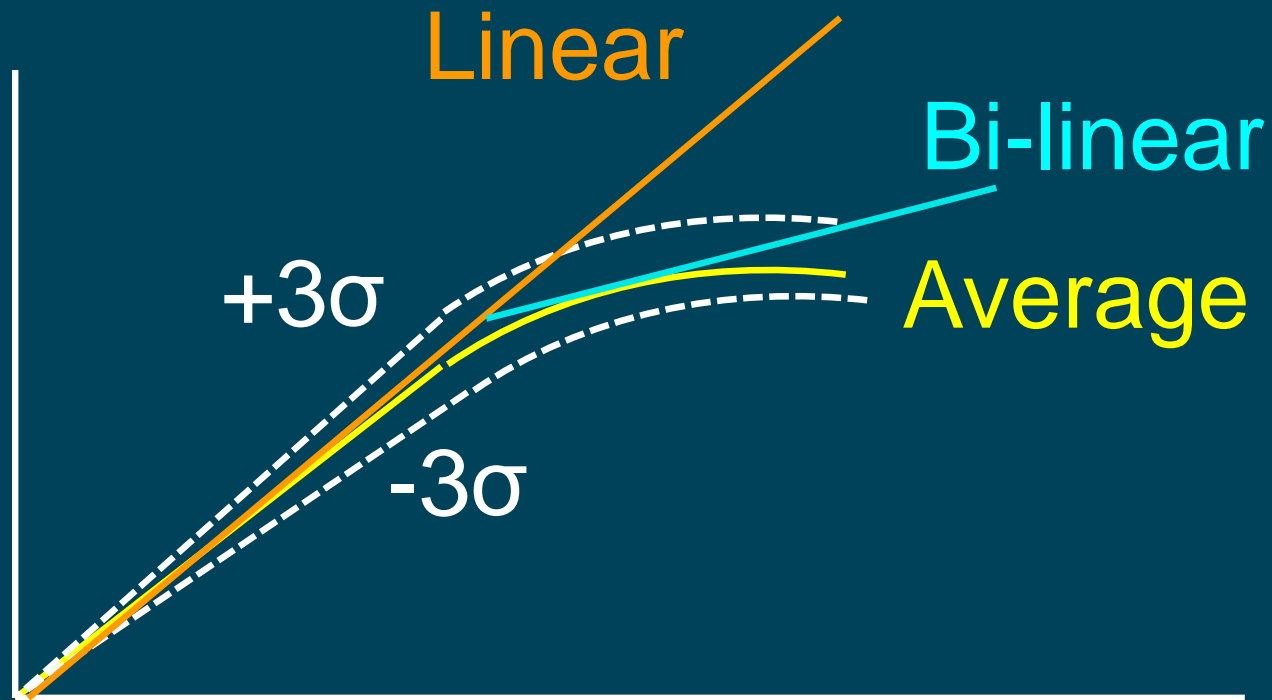
Variation of System Properties (1)

- System properties may be functions of
 - Contact Force (Friction, Contact Resistance)
 - Surface Roughness (Friction, Dielectric Constant)
 - Velocity (Friction)
 - Surface Coatings and Contamination (Contact Resistance, Friction)
 - Environmental Conditions (Contact Resistance, Friction)
 - Time (Contact Resistance)

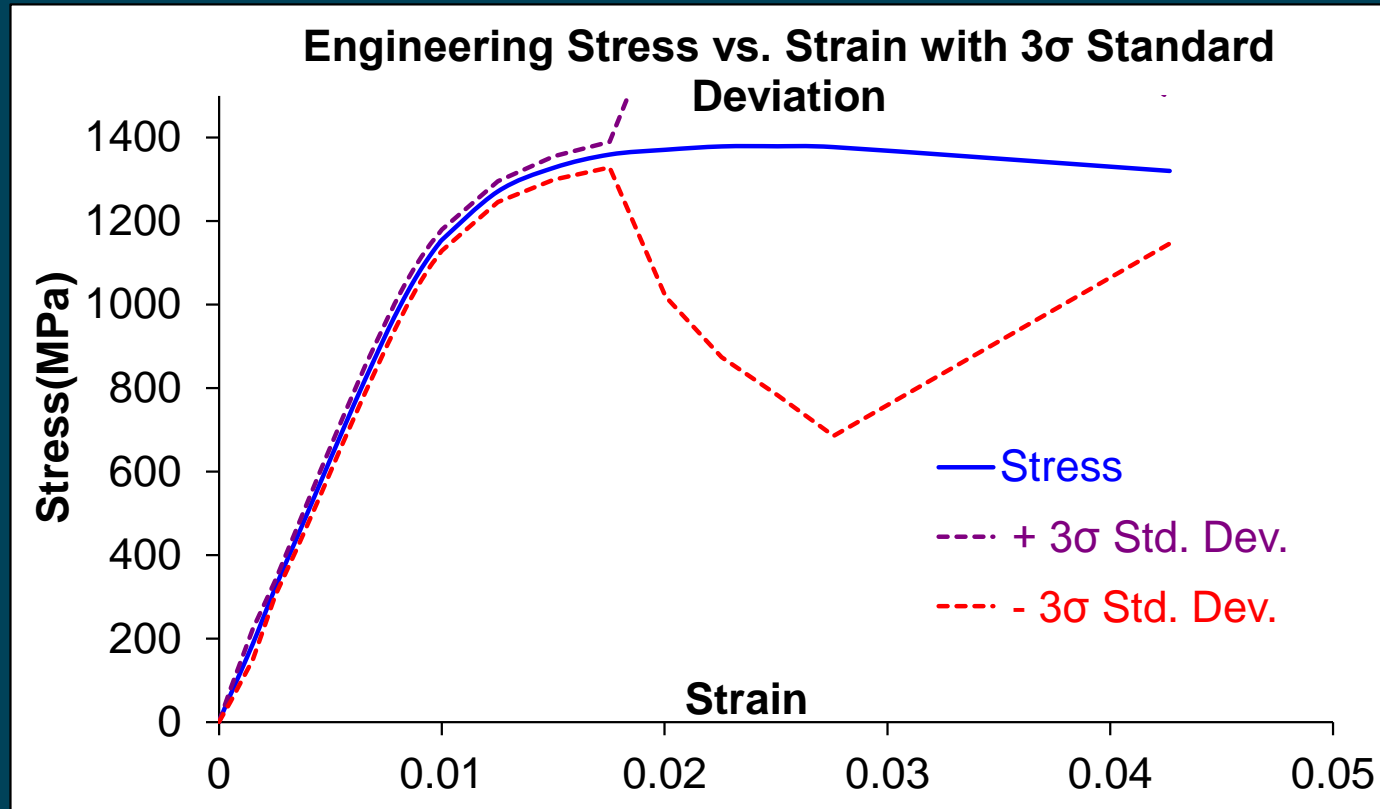
Variation of System Properties (2)

- System properties may be functions of
 - Distance (Capacitance)
 - Length (Resistance, Inductance)
 - Surface Area (Capacitance)
 - Hardness (Wear, Friction, Contact Resistance)
 - Temperature (Contact Resistance)
- Complex Interactions and Confounding!

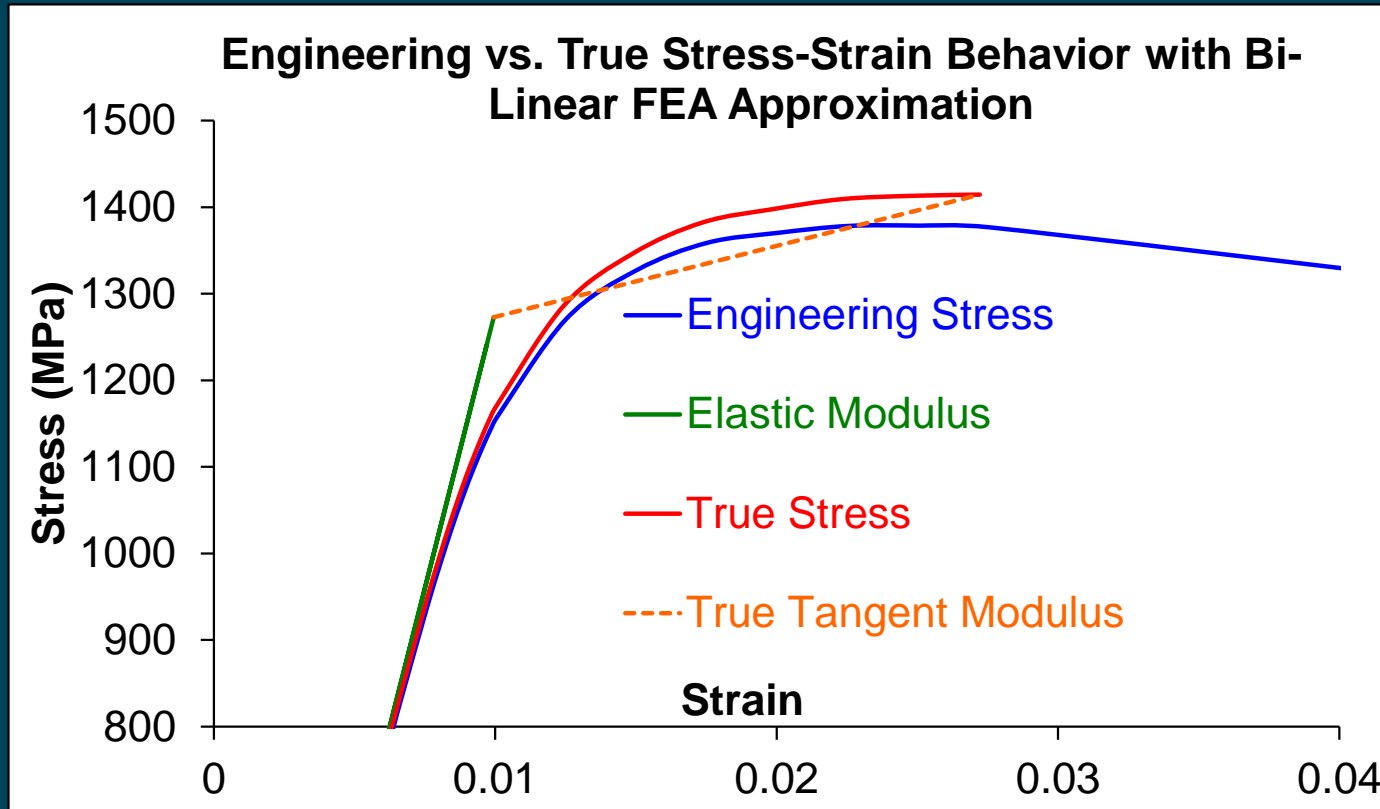
FEA Stress-Strain Behaviors



Variation of Material Properties



Variation of Material Properties



Simulation

- Simulation can be a very powerful tool - when used properly



- But, remember...

It's Only a Model.

